





S/N 10/036389

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Yi Liu et al.

Examiner: Mai-Huong Tran

Serial No.: 10/036389

Group Art Unit: 2818

Filed: January 7, 2002

Docket No.: 884.793US1

Title: THINNED DIE INTEGRATED CIRCUIT PACKAGE

Assignee: Intel Corporation

Customer No: 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

This responds to the Office Action mailed on February 18, 2004. Please amend the above-identified patent application as follows.

05/24/2004 JBR/LINAN 00000085 190743 10036389  
01 FC:1201 172.00 DA